Product / Package Information

Package	SOIC_N_EP (2.41 EP)
Body Size	150 mil
Lead Count	8
Terminal Finish	100 Sn

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.96 E-02	86.2	862000	50.03	500269
Thermosets	Epoxy resin	Proprietary	3.44 E-03	7.5	75000	4.35	43527
Thermosets	Phenol Novolac	9003-35-4	1.84 E-03	4	40000	2.32	23214
Other inorganic materials	Antimony Trioxide	1309-64-4	6.88 E-04	1.5	15000	0.87	8705
Thermosets	Brominated Resin	40039-93-8	2.29 E-04	0.5	5000	0.29	2902
Other inorganic materials	Carbon Black	1333-86-4	1.38 E-04	0.3	3000	0.17	1741
Subtotal			4.59 E-02	100	1000000	58.04	580359

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.88 E-02	97.57	975706	36.46	364560
Copper & its alloys	Iron	7439-89-6	6.73 E-04	2.28	22789	0.85	8515
Copper & its alloys	Zinc	7440-66-6	3.73 E-05	0.13	1263	0.05	472
Copper & its alloys	Phosphorus	7723-14-0	7.16 E-06	0.02	242	0.01	91
Subtotal			2.95 E-02	100.00	1000000	37.36	373637

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.29 E-04	100.0	1000000	0.54	5426

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.80 E-03	100.0	1000000	2.27	22717

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.30 E-04	99.99	1000000	0.29	2909

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	6.48 E-04	100.0	1000000	0.82	8197

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.15 E-04	77.71	777100	0.52	5249
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	1.66 E-05	3.11	31100	0.02	210
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	1.66 E-05	3.11	31100	0.02	210
Other organic materials	Butyrolactone, gamma-	96-48-0	1.66 E-05	3.11	31100	0.02	210
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	1.66 E-05	3.11	31100	0.02	210
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	1.66 E-05	3.11	31100	0.02	210
Other organic materials	Organosilane	TS ref# 10001	1.66 E-05	3.11	31100	0.02	210
Other inorganic materials	Copper(II) oxide	1317-38-0	1.66 E-05	3.11	31100	0.02	210
Other organic materials	Epoxy resin modifier	TS ref# 10038	2.78 E-06	0.52	5200	0.004	35
Subtotal			5.34 E-04	100.00	1000000	0.68	6755

	Weight (g)	Percentage (%)	PPM
Package Totals	**7.91 E-02**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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